

Thermal Stability and Degradation Mechanisms of sputtered ZTO and AlSiO_xN_y Permeation Barrier Layers on PET Substrates under High Humidity

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Motivation: Encapsulation Challenge

Critical Requirement:
Long-term stability of flexible electronics relies heavily on high-performance thin-film permeation barriers.

Environmental Degradation:
Moisture ingress under harsh environmental conditions (elevated temperature & high humidity / Damp-Heat stress) degrades device functionality.

Material Candidates:
Comparison of Zinc Tin Oxide (ZTO) and Aluminum Silicon Oxynitride AlSiO_xN_y for robust encapsulation.

Scientific Gap

Degradation Mechanisms:
Lack of comparative microstructural analysis regarding defect formation, localized corrosion, and phase stability under hygrothermal stress.

Liner Interaction & Interface Stability:
The synergistic degradation between protective polymer liners and inorganic barrier layers under combined thermal and humidity loads remains insufficiently understood.

Dynamic Barrier Behavior:
Limited understanding of reversible vs. irreversible permeation kinetics (WVTR relaxation vs. thermally driven densification) during damp-heat cycling

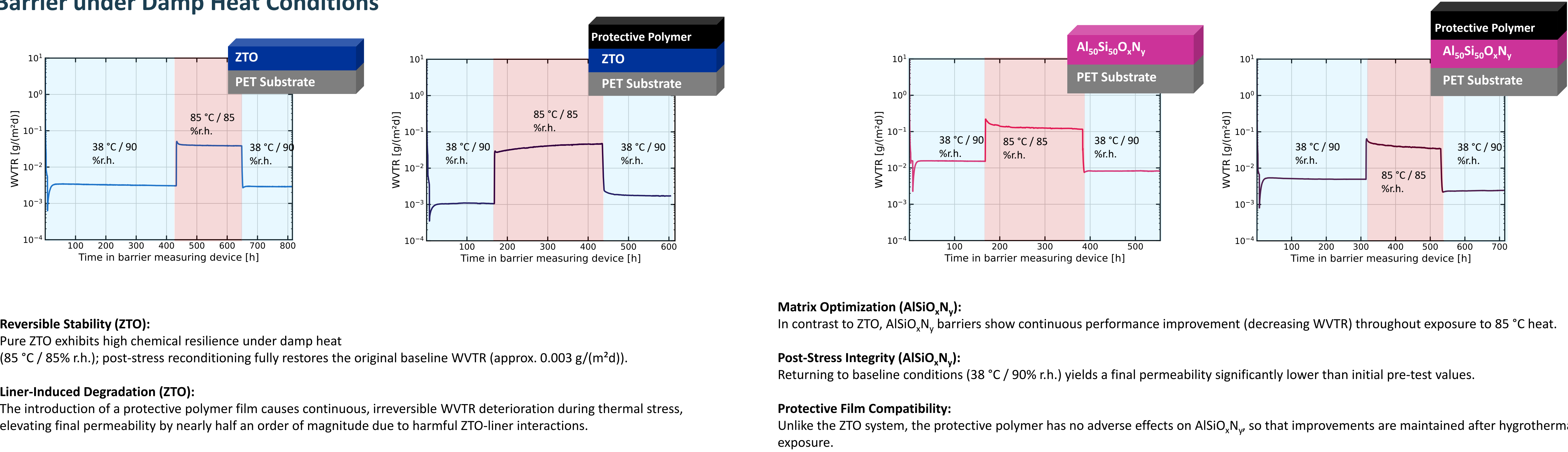
Experimental Workflow

Thin-Film Deposition:
Reactive magnetron sputtering with systematic variation of chemical composition.

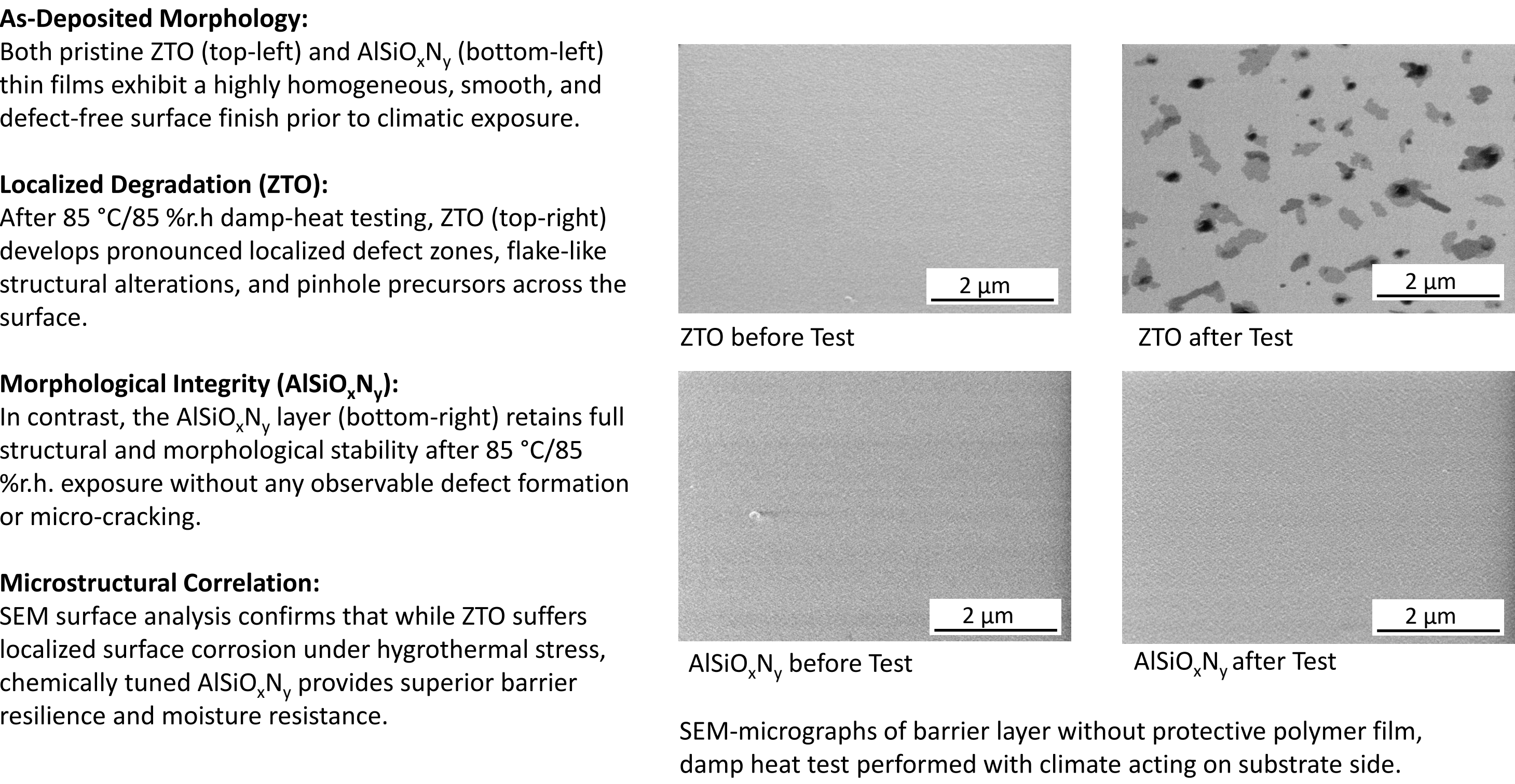
Accelerated Aging:
Damp-Heat testing (elevated temperature & relative humidity).

Microstructural Characterization:
SEM → Surface morphology, defect evolution, and critical failure mode analysis.

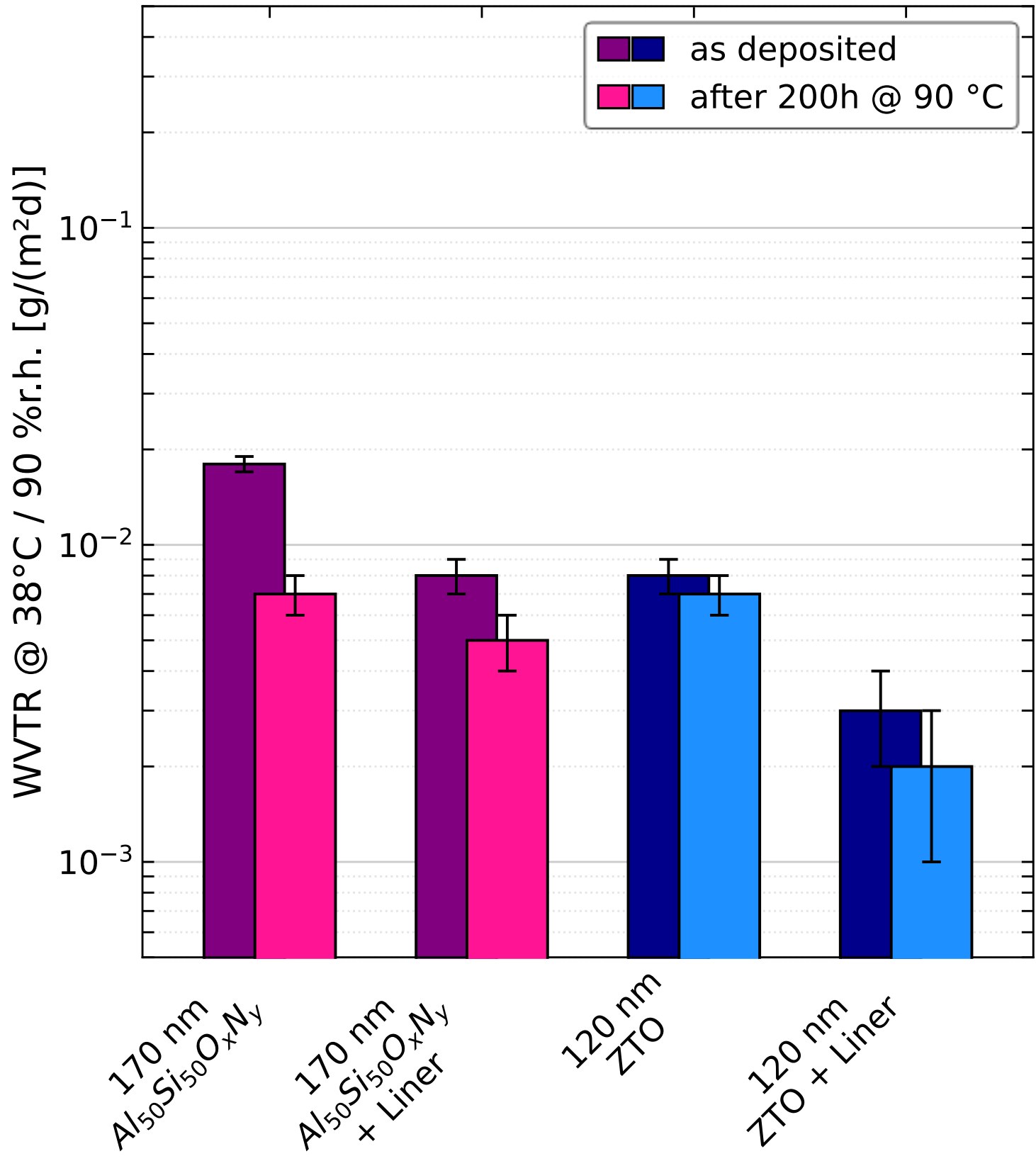
Barrier under Damp Heat Conditions



Morphology after Damp Heat



Heat Treatment



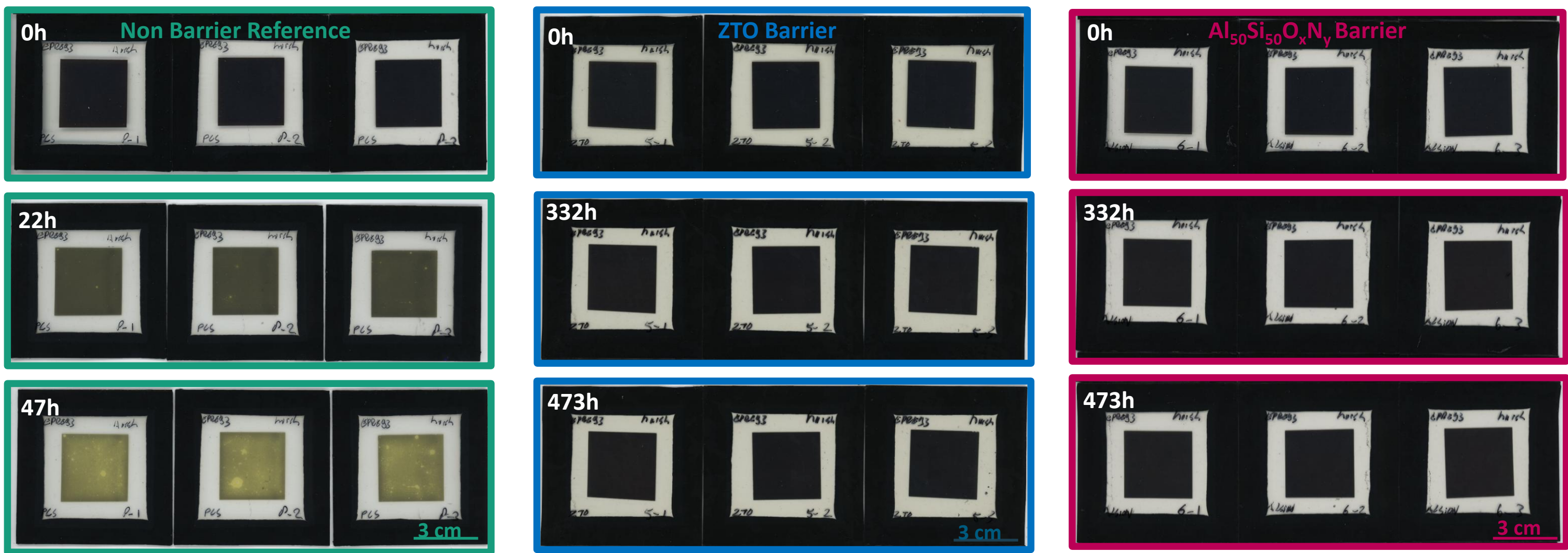
Matrix Densification (AlSiO_xN_y):
Structural compaction and defect closure occur independently of humidity, proving matrix densification is a temperature-driven process.

Dry Heat Stability (ZTO):
ZTO exhibits excellent resilience under dry thermal stress, maintaining nearly constant WVTR values both with (0.003 → 0.002 g/(m²d)) and without a liner (0.008 → 0.007 g/(m²d)).

Synergistic Degradation:
The severe degradation of ZTO liner systems at 85 °C / 85 % r.h. is not driven by heat alone, but requires the combined presence of moisture and the protective polymer layer.

Core Implication:
Thermal stress enhances AlSiO_xN_y barrier performance, whereas ZTO degradation is specifically triggered by hygrothermal (humidity-driven) interactions.

Proof of Concept: Encapsulated Perovskite Modules

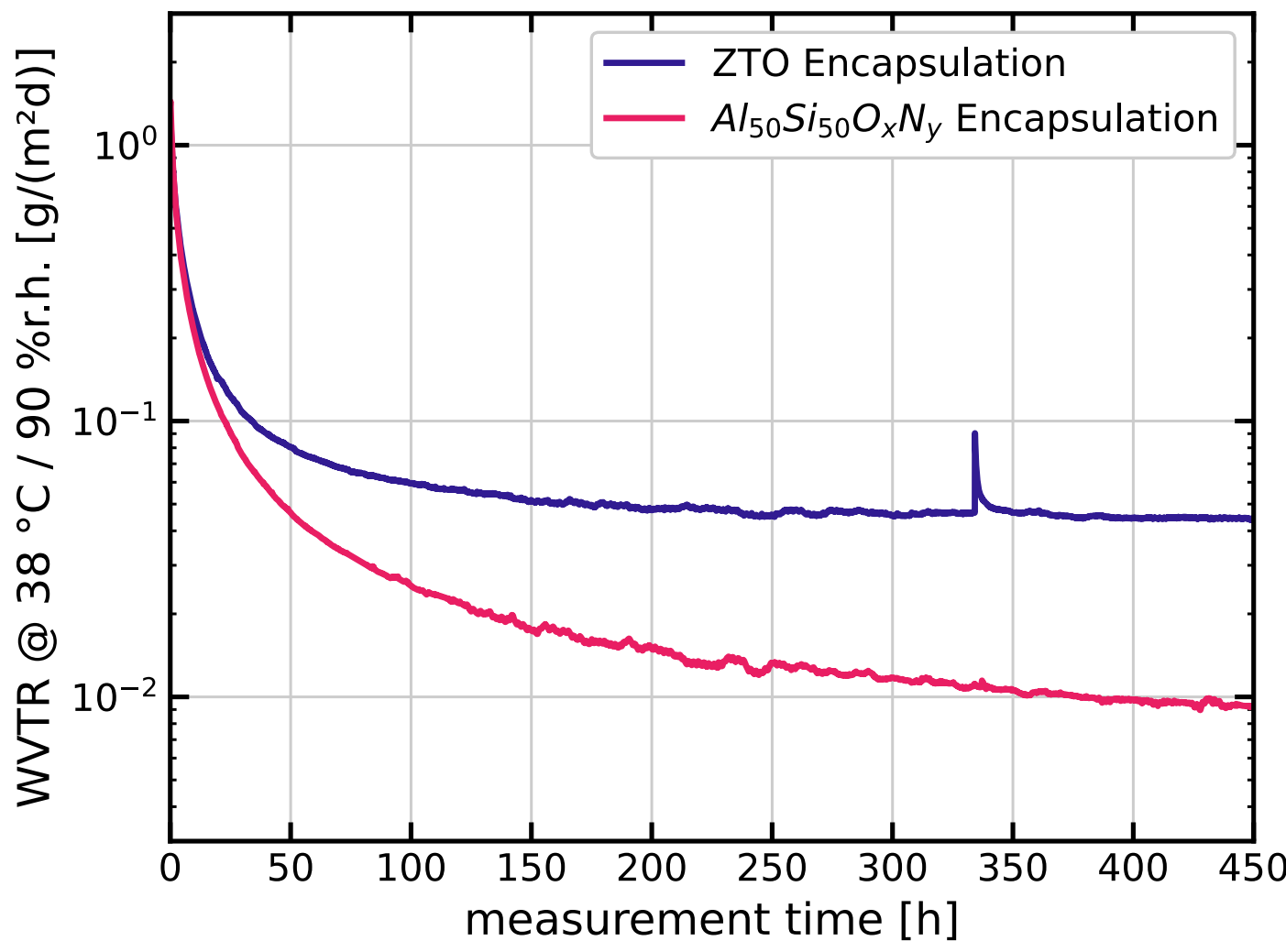


Visual test to evaluate the barrier film on perovskite samples under damp heat (85 °C / 85% r.h.) conditions (7x7 cm² perovskite solar cell modules without contact stripes)

Samples without a barrier degrade rapidly (removed from the test after 47 hours)

The test is still ongoing.

After 473 hours, both encapsulations are stable and show no differences.

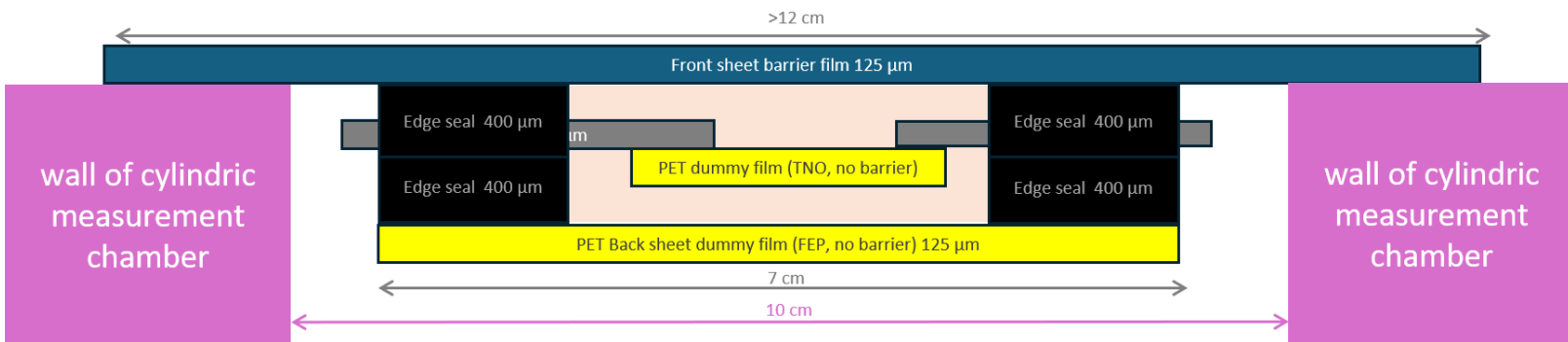


Barrier after encapsulation
(Integral WVTR-measurement of 7x7 cm² dummy solar cell modules without active layers but including all polymer films, contact stripes and front sheet encapsulation with barrier film).

The measurement takes a long time to stabilize.

ZTO appears to be damaged during encapsulation (WVTR of 0.04 g/(m²d) compared to 0.001 g/(m²d) for initial ZTO-barrier foil).

AlSiO_xN_y appears to be less damaged.



Next Steps

Compositional Mapping:
Systematically vary the N/O and Si/Al ratios during reactive sputtering to find the absolute minimum WVTR and optimal optical transparency.

Thickness Variation & Deposition Rates:
Optimize layer thickness down to minimum viable barrier levels to maximize Roll-to-Roll (R2R) throughput while maintaining defect-free morphology.

Interfacial Characterization:
Perform high-resolution cross-sectional analysis at the ZTO/polymer interface to clarify the chemical and mechanical reaction mechanism driving moisture-induced degradation.

Pre-Annealing Protocols:
Test systematic post-deposition thermal annealing of AlSiO_xN_y prior to encapsulation to exploit the matrix densification effect before applying the protective polymer.